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(12) **United States Design Patent**  
**Kaneko et al.**

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(54) **INNER TUBE FOR PROCESS TUBE FOR MANUFACTURING SEMICONDUCTOR WAFERS**

(75) Inventors: **Hirofumi Kaneko**, Oshu (JP); **Atsushi Endo**, Nirasaki (JP)

(73) Assignee: **Tokyo Electron Limited**, Minato-Ku (JP)

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(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/182**

(58) **Field of Classification Search**  
USPC ..... D13/182; D23/266; D7/600.1, 600.2; 118/715, 722, 724, 725; 219/385, 390, 219/486, 520, 523; 83/35, 39; 138/118, 138/118.1, 121, 177, 178; 206/454, 711; 211/41.18; 414/935; 432/247, 253  
See application file for complete search history.

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*Primary Examiner* — Elizabeth J Oswecki

(74) *Attorney, Agent, or Firm* — Burr & Brown, PLLC

(57) **CLAIM**

The ornamental design for an inner tube for process tube for manufacturing semiconductor wafers, as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view of an inner tube for process tube for manufacturing semiconductor wafers showing our new design;

FIG. 2 is a front view thereof;

FIG. 3 is a rear view thereof;

FIG. 4 is a right side thereof;

FIG. 5 is a left side view thereof;

FIG. 6 is a top plan view thereof;

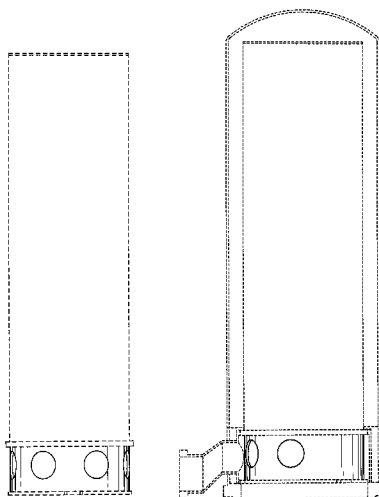
FIG. 7 is a bottom plan view thereof;

FIG. 8 is an enlarged cross-sectional view taken along line 8-8 of FIG. 2; and,

FIG. 9 is another front view thereof, shown in a used condition.

The broken lines shown in the drawings represent portions of the inner tube for process tube for manufacturing semiconductor wafers that form no part of the claimed design.

**1 Claim, 8 Drawing Sheets**



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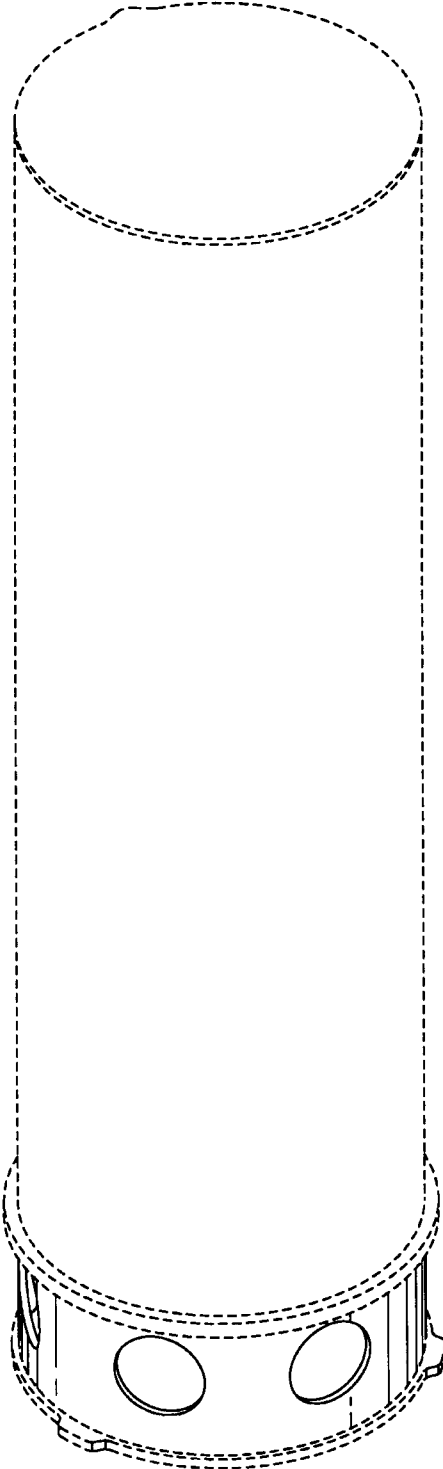


FIG. 1

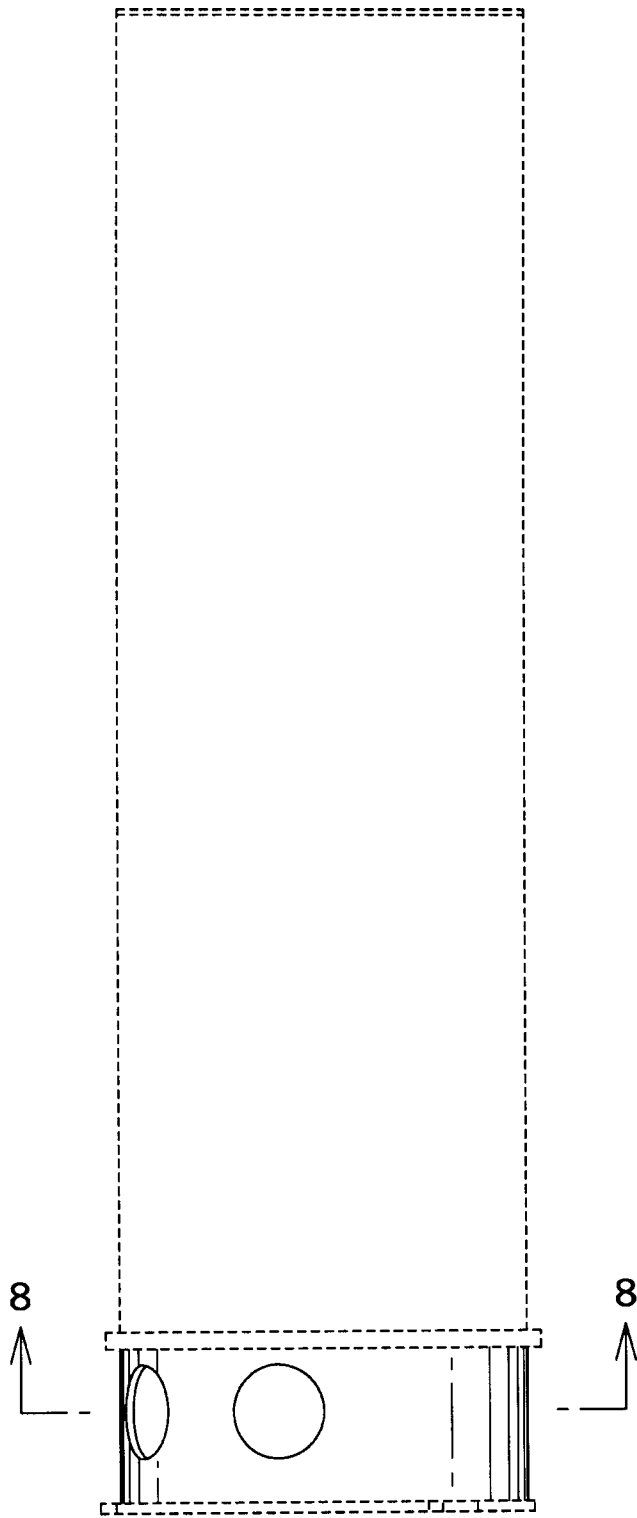


FIG. 2

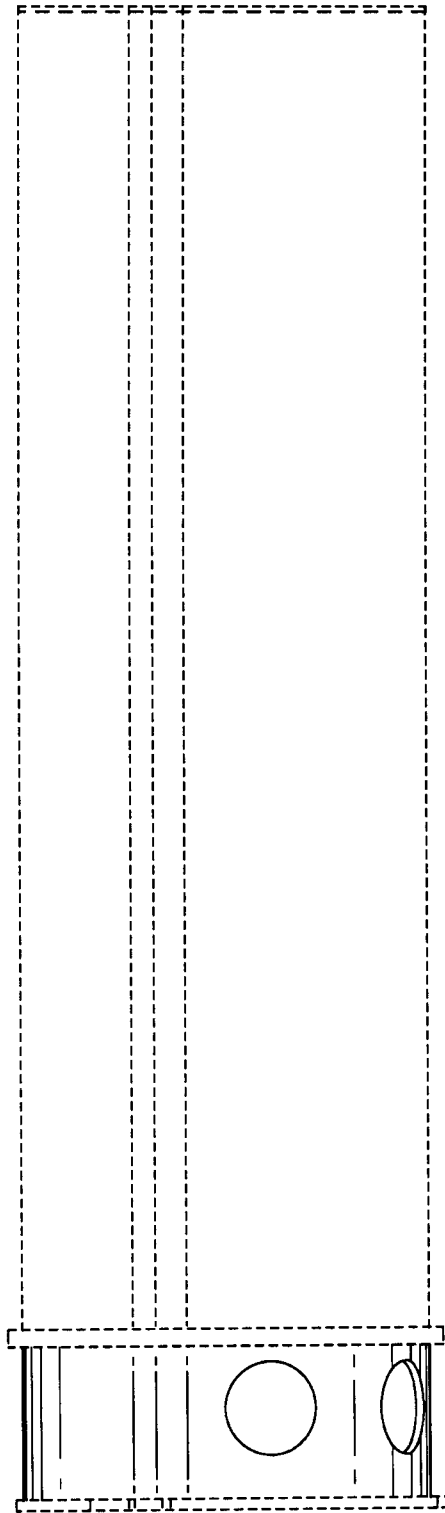


FIG. 3

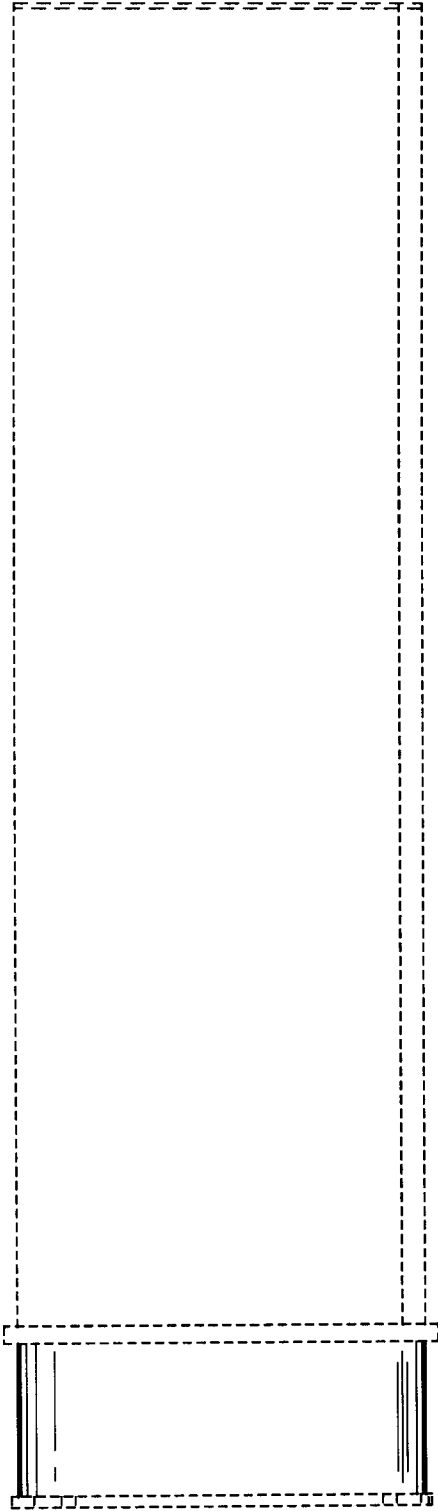


FIG. 4

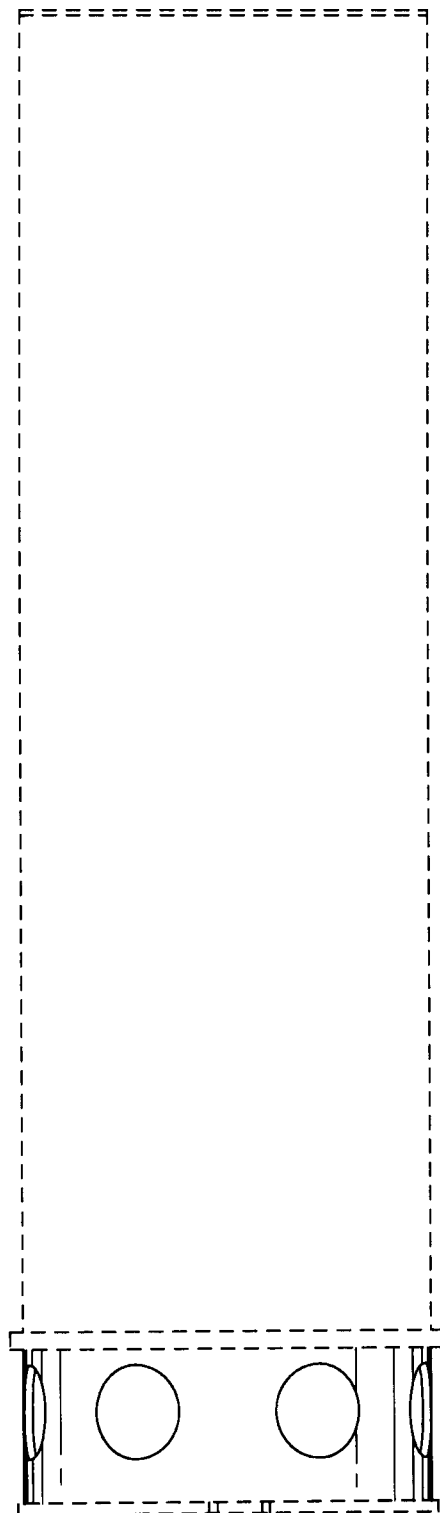


FIG. 5

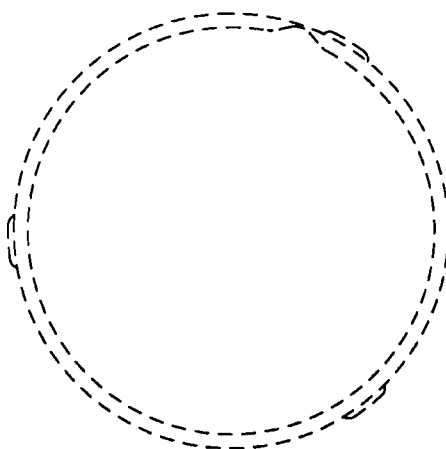


FIG. 6

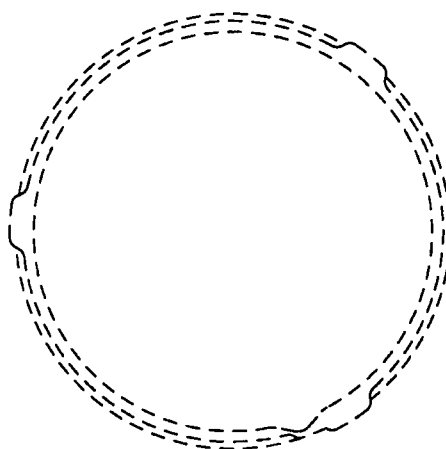


FIG. 7

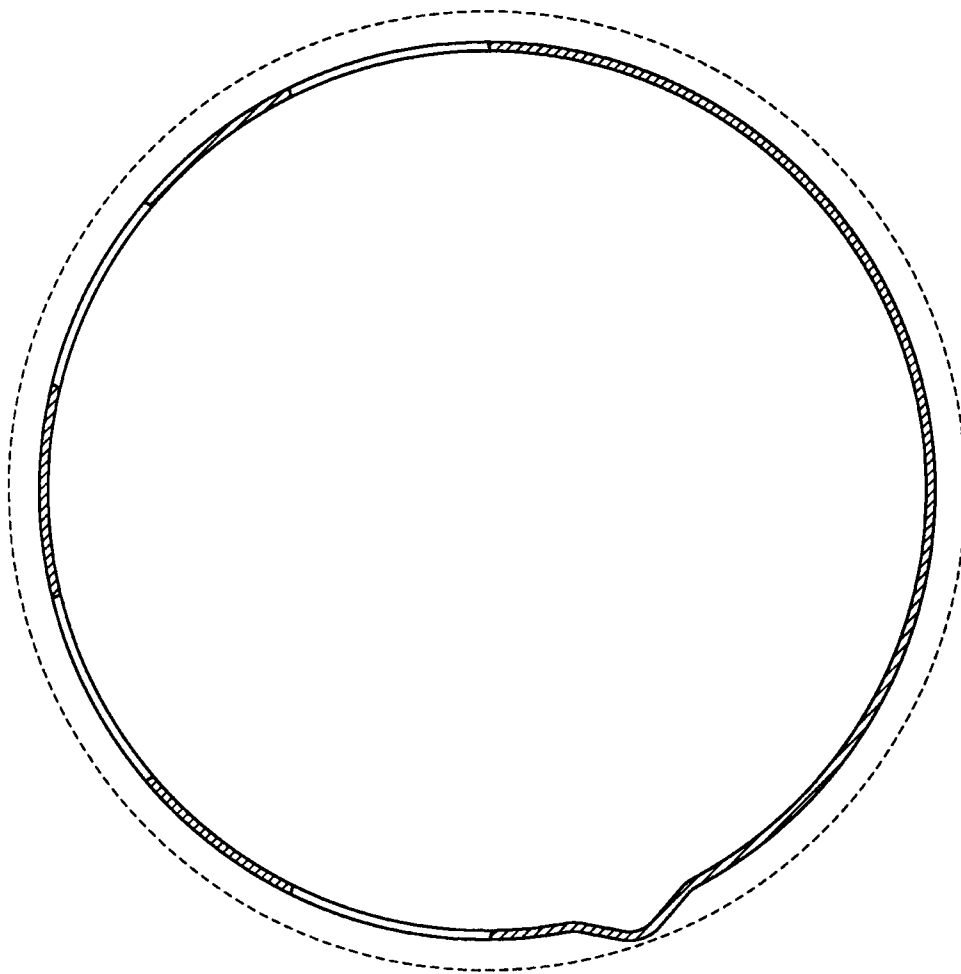


FIG. 8

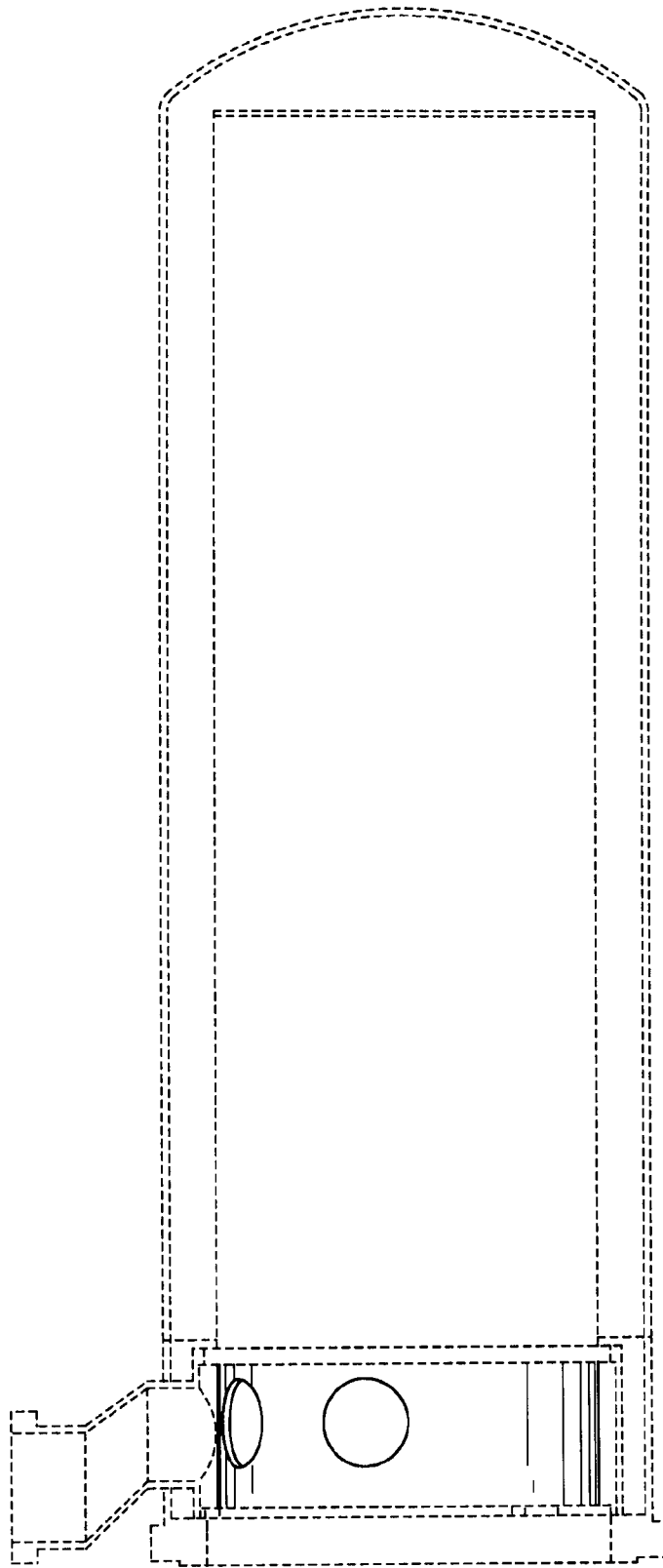


FIG. 9